



ALPHA & OMEGA
SEMICONDUCTOR

AON2408

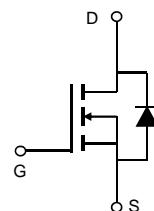
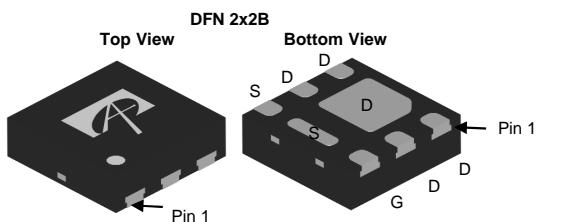
20V N-Channel MOSFET

General Description

The AON2408 combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$. This device is ideal for load switch and battery protection applications.

Product Summary

V_{DS}	20V
I_D (at $V_{GS}=4.5V$)	8A
$R_{DS(ON)}$ (at $V_{GS}=4.5V$)	< 14.5mΩ
$R_{DS(ON)}$ (at $V_{GS}=2.5V$)	< 19mΩ



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current ^G	I_D	8	A
		6	
Pulsed Drain Current ^C	I_{DM}	32	
Power Dissipation ^A	P_D	2.8	W
		1.8	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

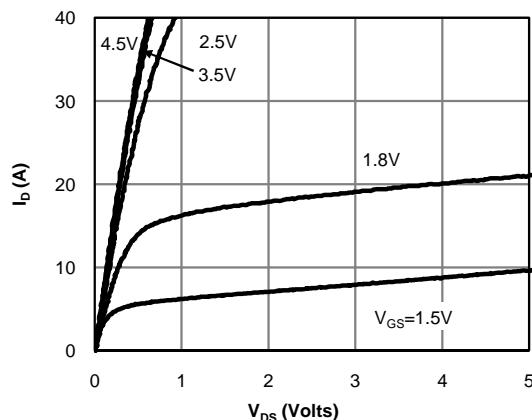
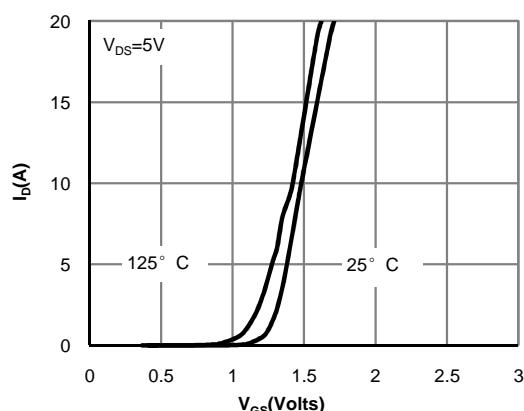
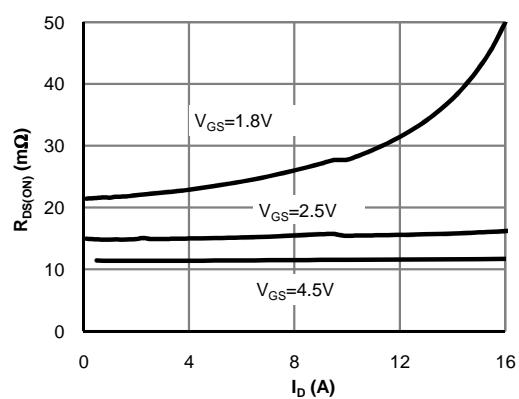
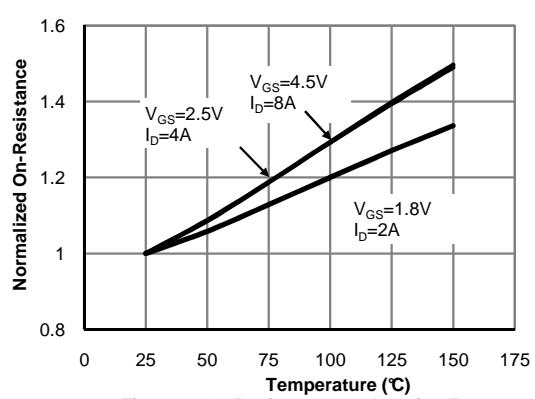
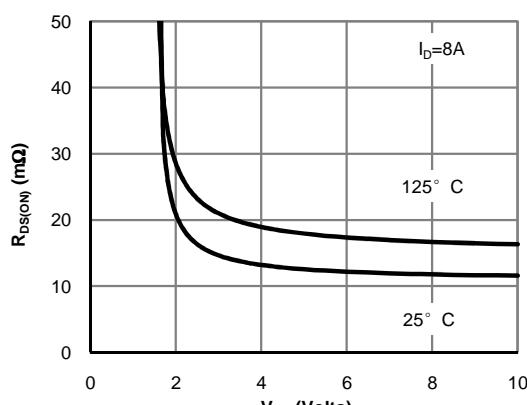
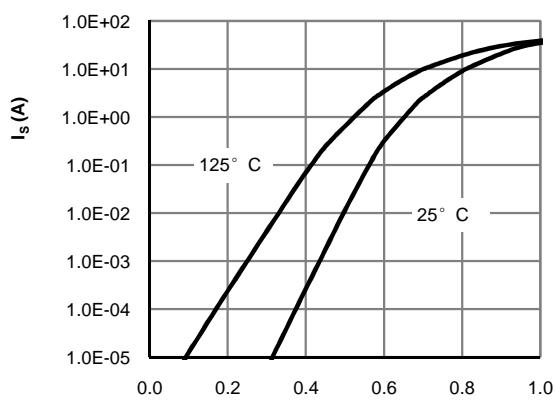
Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A $t \leq 10\text{s}$	$R_{\theta JA}$	37	45	°C/W
Maximum Junction-to-Ambient ^{A,D} Steady-State		66	80	°C/W

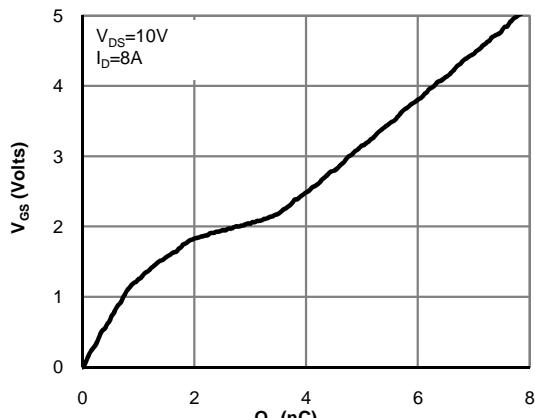
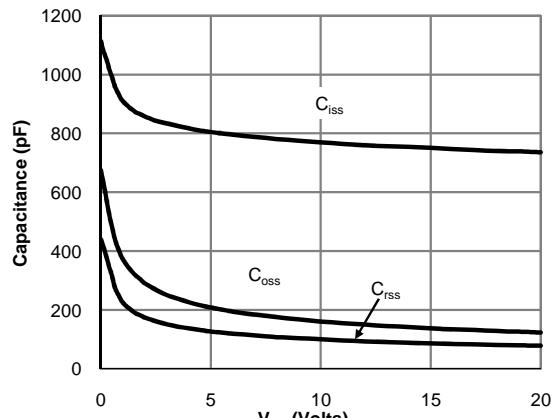
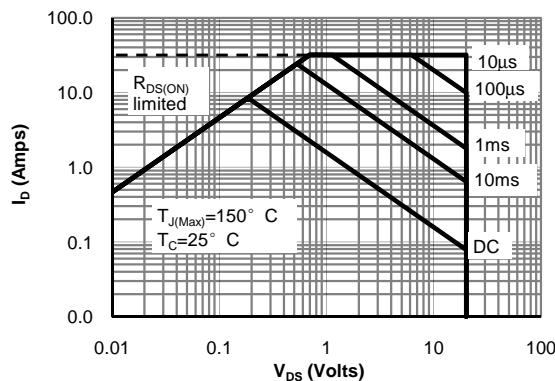
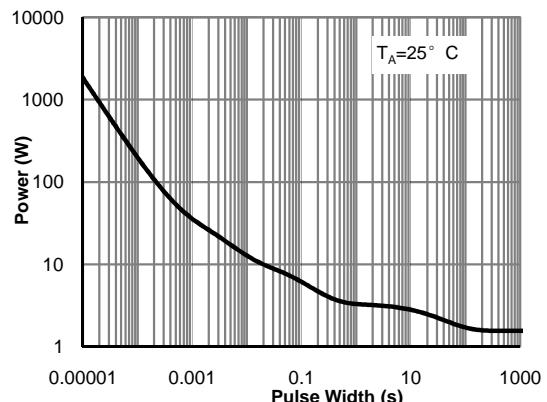
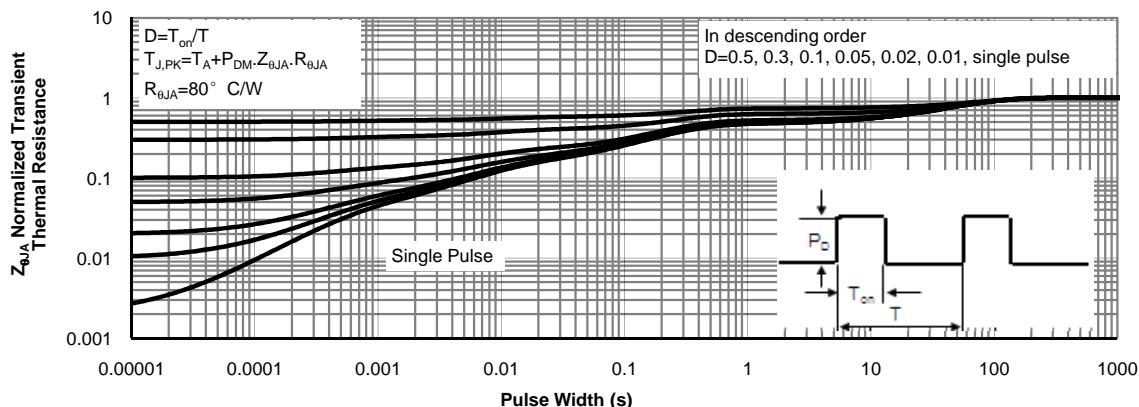
Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

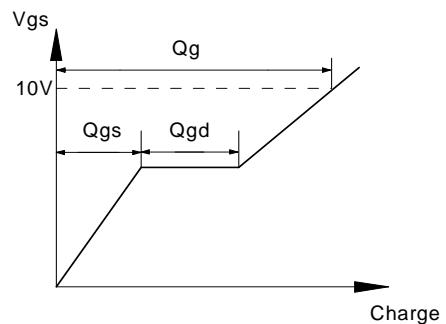
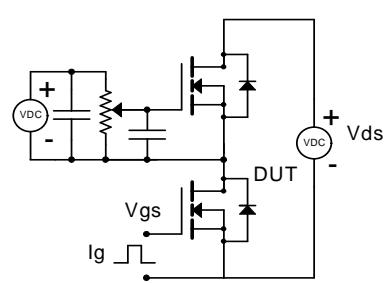
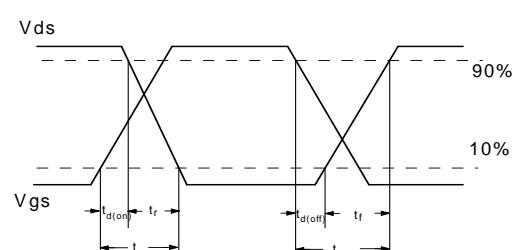
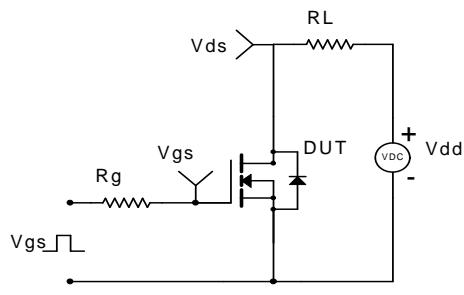
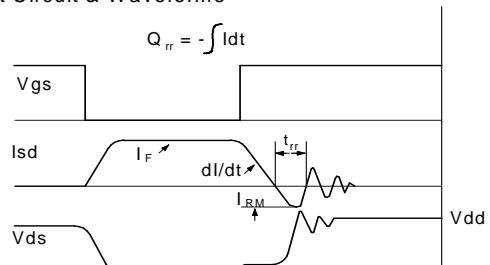
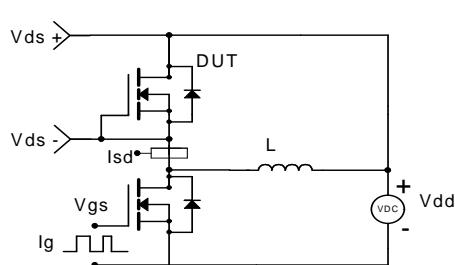
Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	20			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=20\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			1 5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm 12\text{V}$			± 100	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.5	0.83	1.2	V
$I_{\text{D(ON)}}$	On state drain current	$V_{GS}=4.5\text{V}, V_{DS}=5\text{V}$	32			A
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS}=4.5\text{V}, I_D=8\text{A}$ $T_J=125^\circ\text{C}$		11.6	14.5	$\text{m}\Omega$
		$V_{GS}=2.5\text{V}, I_D=4\text{A}$		16.3	20.5	
g_{FS}	Forward Transconductance	$V_{DS}=5\text{V}, I_D=8\text{A}$		50		S
V_{SD}	Diode Forward Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$		0.65	1	V
I_S	Maximum Body-Diode Continuous Current				3.5	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=10\text{V}, f=1\text{MHz}$		782		pF
C_{oss}	Output Capacitance			158		pF
C_{rss}	Reverse Transfer Capacitance			98		pF
R_g	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		2.4		Ω
SWITCHING PARAMETERS						
Q_g	Total Gate Charge	$V_{GS}=4.5\text{V}, V_{DS}=10\text{V}, I_D=8\text{A}$		7		nC
Q_{gs}	Gate Source Charge			1		nC
Q_{gd}	Gate Drain Charge			2.4		nC
$t_{\text{D(on)}}$	Turn-On Delay Time	$V_{GS}=4.5\text{V}, V_{DS}=10\text{V}, R_L=1.25\Omega, R_{\text{GEN}}=3\Omega$		3		ns
t_r	Turn-On Rise Time			4.5		ns
$t_{\text{D(off)}}$	Turn-Off Delay Time			28		ns
t_f	Turn-Off Fall Time			6		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=8\text{A}, dI/dt=100\text{A}/\mu\text{s}$		11		ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=8\text{A}, dI/dt=100\text{A}/\mu\text{s}$		2.7		nC

- A. The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{ C}$. The Power dissipation P_{DSM} is based on $R_{\theta JA}$, $t \leq 10\text{s}$ value and the maximum allowed junction temperature of 150° C . The value in any given application depends on the user's specific board design.
- B. The power dissipation P_D is based on $T_{J(\text{MAX})}=150^\circ\text{ C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
- C. Repetitive rating, pulse width limited by junction temperature $T_{J(\text{MAX})}=150^\circ\text{ C}$. Ratings are based on low frequency and duty cycles to keep initial $T_J=25^\circ\text{ C}$.
- D. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to case $R_{\theta JC}$ and case to ambient.
- E. The static characteristics in Figures 1 to 6 are obtained using $<300\mu\text{s}$ pulses, duty cycle 0.5% max.
- F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(\text{MAX})}=150^\circ\text{ C}$. The SOA curve provides a single pulse rating.
- G. The maximum current rating is package limited.
- H. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{ C}$.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Fig 1: On-Region Characteristics (Note E)

Figure 2: Transfer Characteristics (Note E)

Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

Figure 4: On-Resistance vs. Junction Temperature (Note E)

Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 7: Gate-Charge Characteristics

Figure 8: Capacitance Characteristics

Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

Figure 11: Single Pulse Power Rating Junction-to-Ambient (Note H)

Figure 12: Normalized Maximum Transient Thermal Impedance (Note H)

Gate Charge Test Circuit & Waveform

Resistive Switching Test Circuit & Waveforms

Diode Recovery Test Circuit & Waveforms


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